



TILE-TEC CONFERENCE 2026

4th UK-China Teaching, Learning, and Educational Technology (TILE-TEC) Conference

May 22-24, 2026 | Chengdu, China

<https://tile-tec.org>

About Conference

Theme: Generative AI for Innovation, Sustainability, and Human-Centred Transformation in Transnational Education

The 4th UK-China Teaching, Learning, and Educational Technology (TILE-TEC 2026) Conference will be held in Chengdu, China, from 22–24 May, 2026. The conference aims to bring together academics, researchers, educators, educational developers, students, and industry professionals from the UK, China, and beyond to explore the transformative role of Generative Artificial Intelligence (GenAI) in higher education, with particular emphasis on Transnational Education (TNE).

LIST OF TOPICS

1. Generative AI in Teaching, Learning, and Curriculum Design
2. AI-Enabled Assessment, Feedback, and Academic Integrity
3. Student Engagement, Personalisation, and Learning Analytics
4. Ethics, Trust, and Data Privacy in AI-Powered Education
5. Human-Centred and Sustainable Education in the AI Era
6. Student Support, Wellbeing, and Employability in AI-Driven TNE
7. Redefining the Role of Educators and Academic Leadership
8. Industry 5.0, Innovation, and Entrepreneurship Education
9. Blended, Hybrid, and Immersive Learning Technologies

IMPORTANT DATES

Submission Deadline	March 22, 2026
Acceptance Notification	April 20, 2026
Author Registration	April 27, 2026
Final Manuscript (for full paper)	May 4, 2026
Final Revised Abstract and Slides (for abstract only)	May 4, 2026

CONFERENCE PUBLICATION

Accepted full papers will be invited for oral presentation or poster presentation, and will be included in the conference proceedings and submitted to IEEE Xplore if they meet publication requirements. Accepted full papers that do not meet conference proceeding's requirements will be scheduled exclusively for oral or poster presentation without publication.

CONFERENCE COMMITTEE

General Chair

- Wasim Ahmad, University of Glasgow

Technical Program Committee Co-Chairs

- Haimeng Huang, University of Electronic Science and Technology of China
- Faisal Tariq, University of Glasgow
- Mark Edwards, TNE Institute, Mauritius
- Joseph Tinsley, Xi'an Jiaotong-Liverpool University
- Wenyuan Shi, SWJTU-Leeds Joint School, Southwest Jiaotong University
- Arturo Molina-Cristobal, University of Glasgow Singapore

SUBMISSION GUIDELINE

Full Paper (Presentation and Publication)

- The paper must be written in English.
- All submissions will undergo a peer-review process by the conference committee.
- The paper should be at least of 4 pages or maximum 5 pages length, including all figures, table, and reference. Charges will apply to each extra page.
- The paper should be submitted as a PDF document in .pdf format.
- The submitted paper must be original and must not have been published previously.
- Download the full paper template through: https://tile-tec.org/TILE-TEC2026_Paper_Template.docx or <https://tile-tec.org/conference-latex-template.zip>



Full Paper Submission Link

<https://easychair.org/conferences/?conf=tiletec2026>

Abstract (Presentation Only)

- Abstracts will be considered for oral or poster presentation only. They will not be published in IEEE Xplore.
- The abstract must be written in English.
- Abstracts should be no longer than 300 words and clearly outline the title, purpose, methods, and outcomes of the research or practice being described.
- All submissions will undergo a peer-review process by the conference committee.
- Download the abstract template through: https://tile-tec.org/TILE-TEC2026_Regular_Abstract_Template.docx



Abstract Submission Link

<https://iconf.young.ac.cn/m67XC>

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